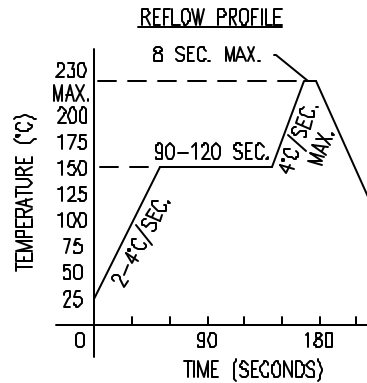
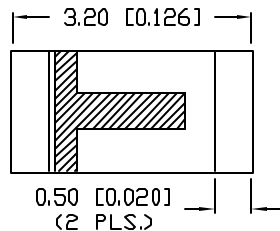
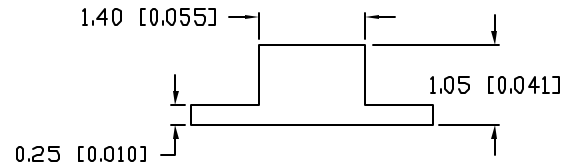
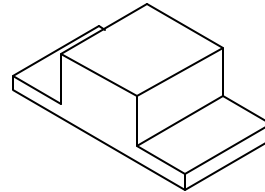


ANODE CATHODE



ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		565		nm	
FORWARD VOLTAGE		2.2	2.6	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY		12		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		120		2x theta	
EMITTED COLOR:	GREEN				
EPOXY LENS FINISH:	GREEN DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	100	mA
STEADY CURRENT	25	mA
POWER DISSIPATION	65	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING TEMP.	-30 TO +85	°C
STORAGE TEMP.	-40 TO +85	°C

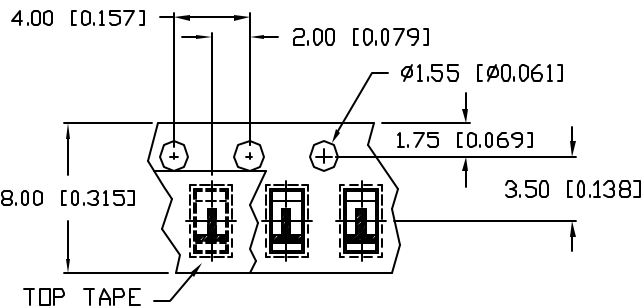
* $t < 10\mu\text{s}$

NOTES:

- 2,000 PIECES PER REEL.
- THE POLARITY MARK IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.

CAUTION: MOISTURE SENSITIVE DEVICE
 1. SHELF LIFE IN SEALED BAG:
 12 MONTHS AT $<40^\circ\text{C}$ AND $<30\%$ RELATIVE HUMIDITY (RH).
 2. AFTER THIS BAG IS OPENED, DEVICES HAVE TO BE MOUNTED WITHIN 48 HOURS OR STORED AT $<30\%$ RH.

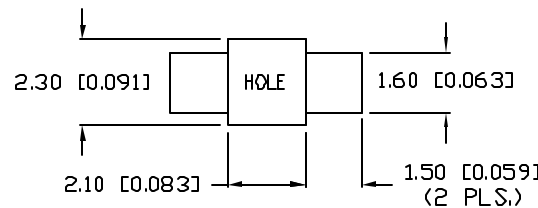
*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (0.002), LEAD LENGTH=±0.75 (±0.030), MIN= ^{+0.00}/_{-0.00} DECIMAL PRECISION, MAX.= ^{+0.00}/_{-0.00} DECIMAL PRECISION



TOP TAPE

TAPE FEED DIRECTION →

RECOMMENDED SOLDER PAD LAYOUT



REV.

PART NUMBER

SML-LXR1206GD-TR

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2.0mm x 1.25mm SURFACE MOUNT LED,
 REVERSE MOUNT, 565nm GREEN LED,
 GREEN DIFFUSED, TAPE AND REEL

RELIABILITY NOTE
 OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY:

CHECKED BY:

APPROVED BY:

DATE: 11.22.00

SS/BC

PAGE: 1 OF 1

SCALE: N/A